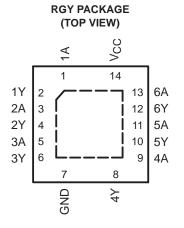
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- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- I_{off} Supports Partial-Power-Down Mode Operation
- Sub 1-V Operable
- Max t_{pd} of 2 ns at 1.8-V
- Low Power Consumption, 10-µA Max I_{CC}
- ±8-mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information



This hex Schmitt-trigger inverter is operational at 0.8-V to 2.7-V V_{CC} , but is designed specifically for 1.65-V to 1.95-V V_{CC} operation.

The SN74AUC14 contains six independent inverters and performs the Boolean function $Y = \overline{A}$. The device functions as six independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

TA PACKAGE[†] ORDERABLE PART NUMBER TOP-SIDE MARKING -40°C to 85°C QFN - RGY Tape and reel SN74AUC14RGYR MS14

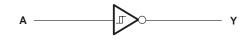
ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	(each inverter)							
11	IPUT A	OUTPUT Y						
	Н	L						
	L	Н						

logic diagram, each inverter (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1) Voltage range applied to any output in the high-impedance or power-off stat	–0.5 V to 3.6 V
(see Note 1)	
Output voltage range, V _O (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Continuous output current, I _O	±20 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{IA} (see Note 2)	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed. 2. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT		
Vcc	Supply voltage		0.8	2.7	V		
VI	Input voltage		0	3.6	V		
Vo	Output voltage		0	VCC	V		
	V _{CC} = 0.8 V V _{CC} = 1.1 V			-0.7			
				-3			
ЮН	High-level output current	V _{CC} = 1.4 V		-5	mA		
		V _{CC} = 1.65 V		-8			
		V _{CC} = 2.3 V		-9			
		V _{CC} = 0.8 V		0.7	,		
		V _{CC} = 1.1 V		3			
IOL	Low-level output current	V _{CC} = 1.4 V		5	mA		
		V _{CC} = 1.65 V		8			
		V _{CC} = 2.3 V		9			
ТА	Operating free-air temperature		-40	85	°C		

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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PARAMETER	TEST CONDITIONS	V _{CC}	MIN	ΤΥΡ [†] ΜΑΧ	UNIT
		0.8 V		0.5	
V _{T+}		1.1 V	0.51	0.86	7
Positive-going input threshold voltage		1.4 V	0.65	1	V
theshold voltage		1.65 V	0.79	1.16	7
		2.3 V	1.11	1.56	7
		0.8 V		0.3	
V _T		1.1 V	0.22	0.53	7
Negative-going input		1.4 V	0.3	0.58	V
threshold voltage		1.65 V	0.39	0.62	1
		2.3 V	0.58	0.87	1
		0.8 V		0.21	
ΔV_{T}		1.1 V	0.25	0.38	7
Hysteresis		1.4 V	0.31	0.5	V
$(V_{T+} - V_{T-})$		1.65 V	0.37	0.62	7
		2.3 V	0.48	0.77	7
	I _{OL} = 100 μA	0.8 V to 2.7 V		0.2	
	I _{OL} = 0.7 mA	0.8 V		0.25	1
	I _{OL} = 3 mA	1.1 V		0.3	
VOL	I _{OL} = 5 mA	1.4 V		0.4	
	I _{OL} = 8 mA	1.65 V		0.45	1
	I _{OL} = 9 mA	2.3 V		0.6	1
II A inputs	V _I = V _{CC} or GND	0 to 2.7 V		±5	μA
l _{off}	$V_{I} \text{ or } V_{O} = 2.7 \text{ V}$	0		±10	μΑ
ICC	$V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$	0.8 V to 2.7 V		10	μA
C _i	$V_{I} = V_{CC}$ or GND	2.5 V		2.5	pF

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at $T_A = 25^{\circ}C$.

switching characteristics over recommended operating free-air temperature range, $C_L = 15 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 0.8 V	V _{CC} = ± 0.		V _{CC} = ± 0.	= 1.5 V .1 V		C = 1.8 0.15 V		V _{CC} = ± 0.	2.5 V 2 V	UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
^t pd	А	Y	8.8	1.2	5.7	0.7	3.9	0.6	1.2	3	0.5	1.8	ns

switching characteristics over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER (INPUT)			C = 1.8 ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		UNIT
		(OUTPUT)	MIN	TYP	MAX	MIN	MAX	
^t pd	А	Y	0.7	1.7	3.5	0.7	2.7	ns



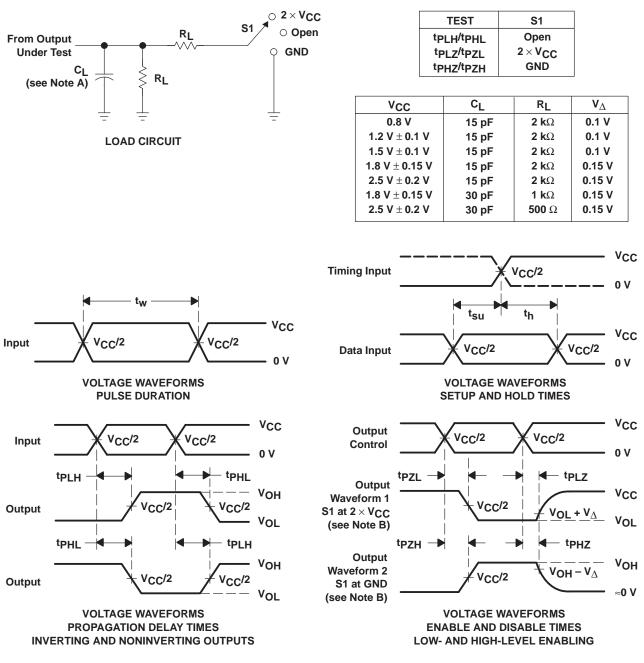
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operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CC} = 0.8 V TYP	V _{CC} = 1.2 V TYP	V _{CC} = 1.5 V TYP	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	UNIT
C _{pd}	Power dissipation capacitance	f = 10 MHz	17	18	19	20	22	pF



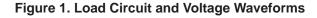
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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , slew rate \geq 1 V/ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tPZL and tPZH are the same as ten.
- G. tPLH and tPHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins I	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AUC14RGYR	ACTIVE	QFN	RGY	14	1000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

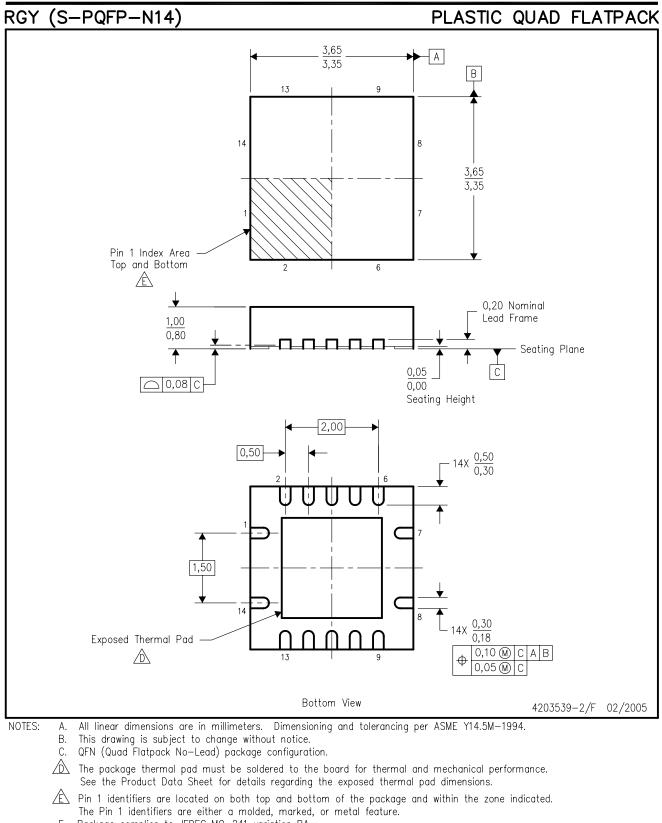
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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MECHANICAL DATA



F. Package complies to JEDEC MO-241 variation BA.



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